

## PATENT ABSTRACTS OF JAPAN

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(71)Applicant : TOKYO ELECTRON LTD

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(72)Inventor : YAMASAKA CHIKAHITO

### (54) PROBE DEVICE

#### (57)Abstract:

**PROBLEM TO BE SOLVED:** To provide a probe device with superior frequency characteristic in which a pin load on a probe card can be reduced, the flatness of the probe card can be maintained, and a thermal effects can be prevented moreover even at high temperature inspection.

**SOLUTION:** In this probe device, lower contact electrodes 13A of a performance board 13 are arranged to be gathered at the central part, and a spacer 16 having through-holes corresponding to the lower contact electrodes 13A is mounted on the performance board 13. Also an interval  $\delta$  is interposed between a probe card 12 and the spacer 16, and a pogo pin 18 elastically brought into contact with each bump 12A and the lower contact electrode 13A corresponding to them is mounted on the through-hole of the spacer 16.

